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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of

New York, New York

Daniel M. Kinzer et al.

Date: January 30, 2008

Serial No.: 10/613,326

Group Art Unit: 2811

Filed: July 3, 2003

Examiner: Ori Nadav

For: VERTICAL CONDUCTION FLIP-CHIP DEVICE WITH BUMP CONTACTS ON
SINGLE SURFACE

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

SUBMISSION

Sir:

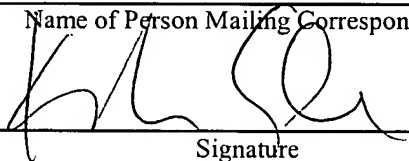
Submitted herewith is a form listing the art for the convenience of the Examiner.

EXPRESS MAIL CERTIFICATE

I hereby certify that this correspondence is being deposited with the United States Postal Service as Express Mail to Addressee (mail label #EV933191700US) in an envelope addressed to: Mail Stop RCE, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on January 30, 2008

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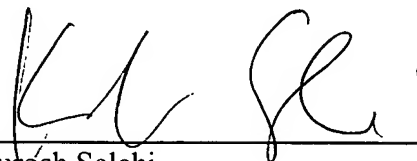


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Respectfully submitted,



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